

RELIABILITY REPORT
FOR
MAX13443EASA+
PLASTIC ENCAPSULATED DEVICES

December 5, 2011

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX13443EASA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX13442E/MAX13444E are fault-protected RS-485 and J1708 transceivers that feature $\pm 80V$ protection from signal faults on communication bus lines. The MAX13442E/MAX13444E feature a reduced slew-rate driver that minimizes EMI and reflections, allowing error-free transmission up to 250kbps. The MAX13443E driver can transmit up to 10Mbps. The high-speed MAX13443E RS-485 transceiver features $\pm 60V$ protection from signal faults on communication bus lines. These transceivers feature foldback current limit. Each device contains one differential line driver with three-state output and one differential line receiver with three-state input. The 1/4-unit-load receiver input impedance allows up to 128 transceivers on a single bus. The devices operate from a 5V supply. True fail-safe inputs guarantee a logic-high receiver output when the receiver inputs are open, shorted, or connected to an idle data line. Hot-swap circuitry eliminates false transitions on the data bus during circuit initialization or connection to a live backplane. Short-circuit current-limiting and thermal-shutdown circuitry protect the driver against excessive power dissipation, and on-chip $\pm 15kV$ ESD protection eliminates costly external protection devices. The MAX13442E/MAX13443E/MAX13444E are available in an 8-pin SO package and are specified over the automotive temperature range.

II. Manufacturing Information

A. Description/Function:	±80V Fault Protected RS-485 Half-Duplex Transceiver with Foldback Current Limit
B. Process:	BCD80N
C. Number of Device Transistors:	1553
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	October 22, 2005

III. Packaging Information

A. Package Type:	150 mil 8L SOIC
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-2601-0087 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	145 X 85 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw:

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 93 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.8 \times 10^{-9}$$

$$\lambda = 11.8 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the BCD80N Process results in a FIT Rate of 0.06 @ 25C and 1.08 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot NA28BA039C D/C 0540)

The RT29-8 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX13443EASA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	48	0	NA23EA042A, D/C 0538
	Biased	& functionality	45	0	IA20BQ001D, D/C 0232
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots